

## ET1890A

### End Termination

#### Description

ET1890A is a nickel plateable silver end termination designed to be compatible on Multilayer ceramic chip capacitors (NPO and X7R bodies). Nickel plating can be done without pre-plate processing due to the low glass content on the fired surface. The rheology of ET1890A is suitable for machine dipping.

#### Key Features

- Nickel plateable-no pre-plate processing Low usage-excellent coverage uniformly Dense fired microstructure



*This picture does not show the packaging of ET1890A and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.*

#### Typical Properties

Viscosity	40 – 50 Kcps, Brookfield RVT SC4 – 14 spindle and 6R utility cup at 10 rpm, 25 °C
Solids	76.5 ± 1.5 %
Alloy Ratio	100
Metal	Ag

#### Recommended Processing Guide

Drying Temperature	150 – 180 °C for 8 minutes Peak temperature of 175 °C for 2 minutes 20 minutes total cycle time
Process Temperature (TDS)	Peak temp: 650 – 800 °C Dwell time at temp, 5 – 7 minutes
Recommended Thinner	RV-372

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#### Warranty

6 months

#### Storage

Store in a dry location at 5 – 25 °C.

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